

1. Record Nr.	UNINA9910133458303321
Titolo	Modern electroplating [[electronic resource] /] / edited by Mordechay Schlesinger, Milan Paunovic
Pubbl/distr/stampa	Hoboken, NJ, : Wiley, c2010
ISBN	1-118-06314-7 1-283-37153-7 9786613371539 0-470-60262-7 0-470-60263-5
Edizione	[5th ed.]
Descrizione fisica	1 online resource (749 p.)
Collana	The ECS series of texts and monographs ; ; 52
Altri autori (Persone)	PaunovicMilan SchlesingerMordechay
Disciplina	671.7/32
Soggetti	Electroplating Metals - Finishing
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	MODERN ELECTROPLATING; CONTENTS; PREFACE; PREFACE TO THE FOURTH EDITION; CONTRIBUTORS; CONVERSION FACTORS; GRAPHICAL CONVERSIONS; THE ELECTROCHEMICAL SOCIETY SERIES; 1 FUNDAMENTAL CONSIDERATIONS; 2 ELECTRODEPOSITION OF COPPER; 3 ELECTRODEPOSITION OF NICKEL; 4 ELECTRODEPOSITION OF GOLD; 5 ELECTROLESS AND ELECTRODEPOSITION OF SILVER; 6 TIN AND TIN ALLOYS FOR LEAD-FREE SOLDER; 7 ELECTRODEPOSITION OF CHROMIUM; 8 ELECTRODEPOSITION OF LEAD AND LEAD ALLOYS; 9 ELECTRODEPOSITION OF TIN-LEAD ALLOYS; 10 ELECTRODEPOSITION OF ZINC AND ZINC ALLOYS; 11 ELECTRODEPOSITION OF IRON AND IRON ALLOYS 12 PALLADIUM ELECTROPLATING 13 ELECTROCHEMICAL DEPOSITION PROCESS FOR ULSI INTERCONNECTION DEVICES; 14 ELECTRODEPOSITION OF SEMICONDUCTORS; 15 DEPOSITION ON NONCONDUCTORS; 16 CONDUCTIVE POLYMERS: ELECTROPLATING OF ORGANIC FILMS; 17 ELECTROLESS DEPOSITION OF COPPER; 18 ELECTROLESS DEPOSITION OF NICKEL; 19 ELECTROCHEMICAL

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27 APPLICATIONS TO MAGNETIC RECORDING AND MICROELECTRONIC TECHNOLOGIES; 28 MICROELECTROMECHANICAL SYSTEMS; 29 ANALYSIS OF ELECTROPLATED FILMS USING DUAL-BEAM FIB/SEM AND TEM TECHNIQUES; 30 IONIC LIQUID TREATMENTS FOR ENHANCED CORROSION RESISTANCE OF MAGNESIUM-BASED SUBSTRATES; APPENDIX; INDEX

Sommario/riassunto

The definitive resource for electroplating, now completely up to date With advances in information-age technologies, the field of electroplating has seen dramatic growth in the decade since the previous edition of Modern Electroplating was published. This expanded new edition addresses these developments, providing a comprehensive, one-stop reference to the latest methods and applications of electroplating of metals, alloys, semiconductors, and conductive polymers. With special emphasis on electroplating and electrochemical plating in nanotechnologies, data storage, and medical app
